#### 504350583 05/03/2017

### PATENT ASSIGNMENT COVER SHEET

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| SUBMISSION TYPE:      | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT     |

#### **CONVEYING PARTY DATA**

| Name           | Execution Date |
|----------------|----------------|
| SHENG ZHANG    | 04/07/2017     |
| WEN-BO DING    | 04/07/2017     |
| ZHI-RUI SHENG  | 04/07/2017     |
| CHIEN-EN HSU   | 04/07/2017     |
| CHIEN-KEE PANG | 04/07/2017     |

#### RECEIVING PARTY DATA

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| City:                               | HSINCHU  |  |  |
| State/Country:                      | TAIWAN   |  |  |

#### **PROPERTY NUMBERS Total: 1**

| Property Type       | Number   |
|---------------------|----------|
| Application Number: | 15586102 |

#### **CORRESPONDENCE DATA**

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| ATTORNEY DOCKET NUMBER: | JCLA68751  |
|-------------------------|--|
| NAME OF SUBMITTER:      | JIAWEI HUANG   |
| SIGNATURE:              | /JIAWEI HUANG/   |
| DATE SIGNED:            | 05/03/2017   |
|                         | This document serves as an Oath/Declaration (37 CFR 1.63). |

**Total Attachments: 7** 

source=68751\_Combined\_Declaration\_Assignment#page1.tif

**PATENT** REEL: 042232 FRAME: 0364 504350583



PATENT REEL: 042232 FRAME: 0365

| ☑ Declaration Submitted With Initial Filing        |  |
|--|--|
| OR   | ,  |
| ☐ Declaration Submitted After Initial Filing       | (surcharge 37 CFR 1.16(f) required)            |
| (Title of the In                                   | vention)                                       |
| WAFER LEVEL PACK                                   | AGING METHOD                                   |
|  |  |
|  |  |
| As a below named inventor (hereinafter design      | ated as the undersigned), I hereby declare     |
| that:  |  |
| This declaration is directed to:                   |  |
| _  |  |
| ☑ The attached application, OR                     |  |
| ☐ United States Application Number or P            | CT International application number            |
| Filed on   |  |
|  |  |
| The characidentified application was made or or    | therized to be made by me                      |
| The above-identified application was made or au    | inonzed to be made by me.                      |
| I believe I am the original inventor or an origina | I joint inventor of a claimed invention in the |
| application.                                       |  |
| The undersigned hereby acknowledge that            | any willful false statement made in this       |
| declaration is punishable under 18 U.S.C. 1001 i   | •  |
| (5) years, or both.                                | •  |
|  |  |

#### DECLARATION AND ASSIGNMENT

#### FOR UTILITY OR DESIGN PATENT APPLICATION

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS 1. United Microelectronics Corp.

of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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| Signature: | ZHANG | SHENGO | Date: | 07/ | 'v\/ | 2017 |
|------------|-------|--------|-------|-----|------|------|
|------------|-------|--------|-------|-----|------|------|

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|-----------------------|-------|-------|-------|

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| Signature: | ZHI RUL | SHENG | Date: | 07/ | 04/2017 |  |
|------------|---------|-------|-------|-----|---------|--|
| _          |         |       |       |     |         |  |

Legal Name of Additional Joint Inventor, if any: Zhi-Rui Sheng

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